



## **Rectifier Diode**

# **Target Information**

DS5415-2.0 October 2001

### Replaces November 2000, version DS5415-1.1

# FEATURES

- Optimised For High Current Rectifiers
- High Surge Capability
- Very Low On-state Voltage

### **APPLICATIONS**

- Electroplating
- Power Supplies
- Welding

### **VOLTAGE RATINGS**

Part and Ordering Number	Repetitive Peak Reverse Voltage V <sub>RRM</sub> V	Conditions
RD33FG06	600	$V_{RSM} = V_{RRM}$
RD33FG05	500	KSIWI KKIWI
RD33FG04	400	
RD33FG03	300	
RD33FG02	200	
RD33FG01	100	

### **ORDERING INFORMATION**

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

### RD33FG03

Note: Please use the complete part number when ordering and quote this number in any future correspondance relating to your order.

### **KEY PARAMETERS**

$V_{RRM}$		600V
I <sub>F(AV)</sub>	(max)	3997A
I <sub>FSM</sub>	(max)	46750A

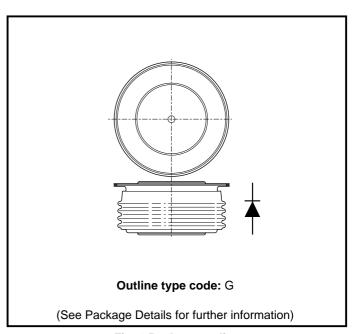


Fig. 1 Package outline



## **CURRENT RATINGS**

# $T_{case} = 75$ °C unless otherwise stated

Symbol	Parameter	Conditions	Max.	Units			
Double Sid	Double Side Cooled						
I <sub>F(AV)</sub>	Mean forward current	Half wave resistive load	3997	А			
I <sub>F(RMS)</sub>	RMS value	-	6278	А			
I <sub>F</sub>	Continuous (direct) forward current	-	6358	А			
Single Side Cooled (Anode side)							
I <sub>F(AV)</sub>	Mean forward current	Half wave resistive load	2831	Α			
I <sub>F(RMS)</sub>	RMS value	-	4447	А			
I <sub>F</sub>	Continuous (direct) forward current	-	4401	А			

# $T_{case} = 85^{\circ}C$ unless otherwise stated

Symbol	Parameter	Test Conditions	Max.	Units			
Double Sid	Double Side Cooled						
I <sub>F(AV)</sub>	Mean forward current	Half wave resistive load	3830	А			
I <sub>F(RMS)</sub>	RMS value	-	6010	А			
I <sub>F</sub>	Continuous (direct) forward current	-	6080	А			
Single Side Cooled							
I <sub>F(AV)</sub>	Mean forward current	Half wave resistive load	2710	А			
I <sub>F(RMS)</sub>	RMS value	-	4260	А			
l <sub>F</sub>	Continuous (direct) forward current	-	4210	А			



# **SURGE RATINGS**

Symbol	Parameter	Test Conditions	Max.	Units
I <sub>FSM</sub>	Surge (non-repetitive) forward current	10ms half sine, T <sub>case</sub> = 175°C	37.4	kA
l²t	I <sup>2</sup> t for fusing	V <sub>R</sub> = 50% V <sub>RRM</sub> - 1/4 sine	7.0 x 10 <sup>6</sup>	A²s
I <sub>FSM</sub>	Surge (non-repetitive) forward current	10ms half sine, T <sub>case</sub> = 175°C	46.75	kA
l²t	I <sup>2</sup> t for fusing	V <sub>R</sub> = 0	10.93 x 10 <sup>6</sup>	A²s

## THERMAL AND MECHANICAL RATINGS

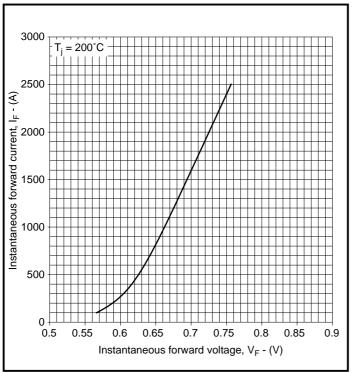
Symbol	Parameter	Test Conditions		Min.	Max.	Units
R <sub>th(j-c)</sub>	Thermal resistance - junction to case	Double side cooled	DC	-	0.032	°CW
		Single side cooled	Anode DC	-	0.064	°CW
			Cathode DC	-	0.064	°CW
R <sub>th(c-h)</sub>	Thermal resistance - case to heatsink	Clamping force 12.0kN	Double side	-	0.008	°CW
		(with mounting compound)	Single side	-	0.016	°CW
T <sub>vj</sub>	Virtual junction temperature	Forward (conducting)		-	225	°C
		Reverse (blocking)		-	200	°C
T <sub>stg</sub>	Storage temperature range			<b>-</b> 55	200	°C
F <sub>m</sub>	Clamping force			10.8	13.2	kN

## **CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Min.	Max.	Units
I <sub>RM</sub>	Peak reverse current	At V <sub>RRM</sub> , T <sub>case</sub> = 200°C	-	50	mA
l <sub>rr</sub>	Peak reverse recovery current	$I_F = 1000A$ , $dI_{RR}/dt = 3A/\mu s$ ,	-	30	Α
Q <sub>s</sub>	Total stored charge	$T_{case} = 200^{\circ}C, V_{R} = 100V$	-	160	μС
V <sub>TO</sub>	Threshold voltage	At T <sub>vj</sub> = 200°C	-	0.6	V
r <sub>T</sub>	Slope resistance	At T <sub>vj</sub> = 200°C	-	0.0872	mΩ



## **CURVES**



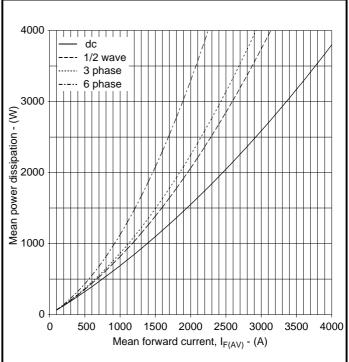


Fig. 2 Maximum (limit) forward characteristics

Fig. 3 Power dissipation

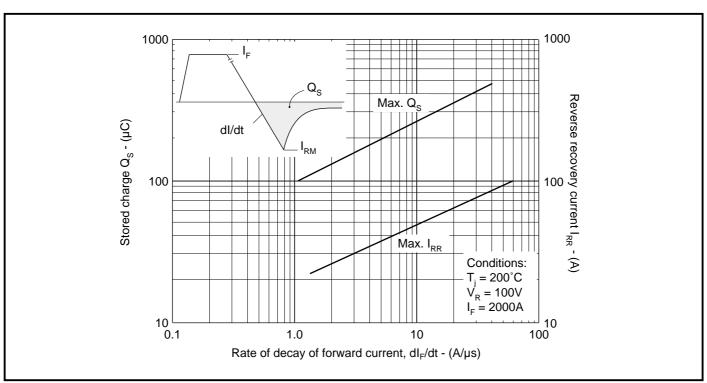
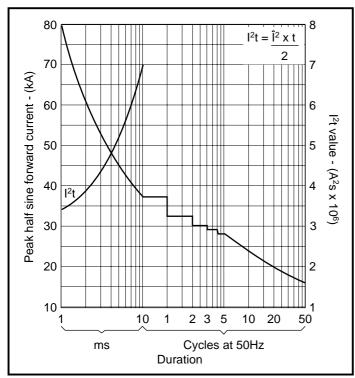


Fig. 4 Maximum stored charge and reverse recovery current vs dl/dt







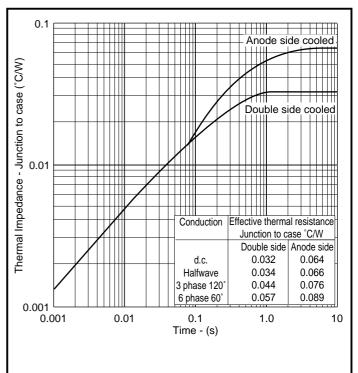
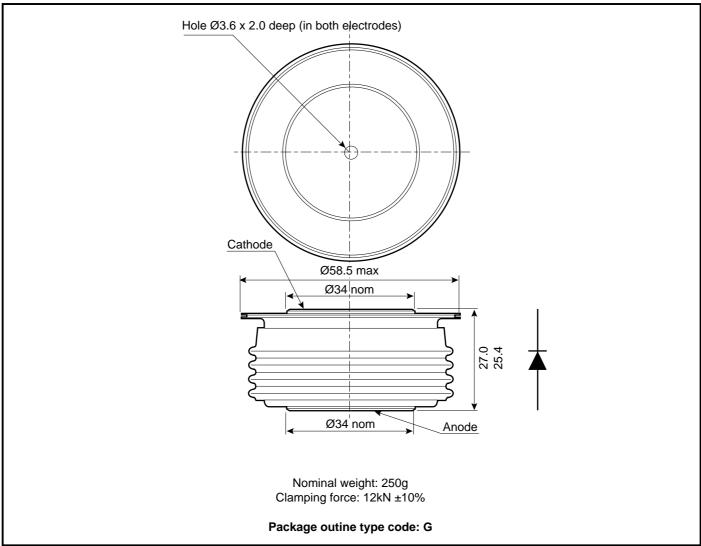


Fig. 6 Maximum (limit) transient thermal impedance



### **PACKAGE DETAILS**

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



#### Note:

1. Package maybe supplied with pins and/or tags.



### **POWER ASSEMBLY CAPABILITY**

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

#### **HEATSINKS**

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.



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Target Information: This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

Advance Information: The product design is complete and final characterisation for volume production is well in hand.

**No Annotation:** The product parameters are fixed and the product is available to datasheet specification.

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